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# 4/Response  
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE  
TECHNOLOGY CENTER 2800

**In re Application of:**

Sambasivam, et al.

**Serial No.:** 10/033,854 ✓

**Filed:** December 19, 2001

**For:** UNDERFILL MATERIALS  
DISPENSED IN A FLIP CHIP  
PACKAGE BY WAY OF A  
THROUGH HOLE

**Examiner:** Scott Brairton

**Group Art Unit:** 2823

**Attorney Docket No.:** 42390.P13267

CERTIFICATE OF MAILING

I hereby certify that this paper or fee along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail (under 37 C.F.R. § 1.8(a)) on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner of Patents and Trademarks, Washington, D.C. 20231.

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RESPONSE

Hon. Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

In response to the Official Action mailed June 5, 2002, please consider the following  
remarks: